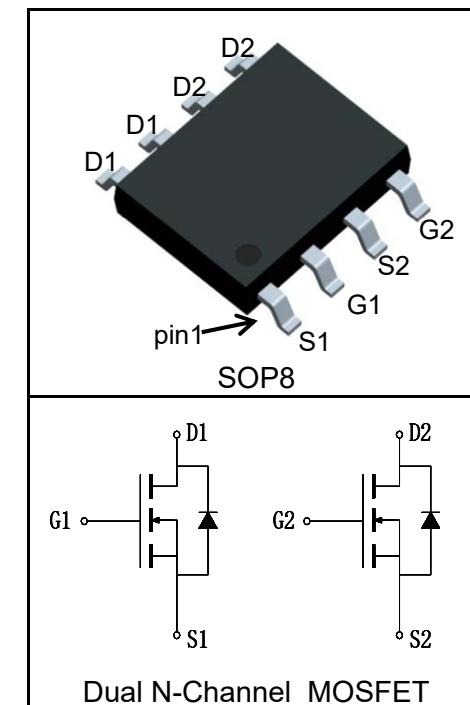


Features

- 30V/8.8A,
 $R_{DS\ (ON)} = 16m\Omega$ (Typ.)@ $V_{GS}=10V$
- $R_{DS\ (ON)} = 24m\Omega$ (Typ.)@ $V_{GS}=4.5V$
- Low $R_{DS\ (ON)}$
- Super High Dense Cell Design
- Reliable and Rugged

Pin Description



Applications

- Power Management
- Battery Protection



Halogen-Free

Absolute Maximum Ratings

| Symbol | Parameter | Rating | Unit |
|--|---|------------------|--------------|
| Common Ratings ($T_A=25^\circ C$ Unless Otherwise Noted) | | | |
| V_{DSS} | Drain-Source Voltage | 30 | V |
| V_{GSS} | Gate-Source Voltage | ± 20 | |
| T_J | Maximum Junction Temperature | 150 | $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| I_S | Diode Continuous Forward Current | $T_A=25^\circ C$ | A |
| Mounted on Large Heat Sink | | | |
| $I_{DP}^{(1)}$ | 300 μs Pulse Drain Current Tested | $T_A=25^\circ C$ | 35 |
| $I_D^{(2)}$ | Continuous Drain Current($V_{GS}=4.5V$) | $T_A=25^\circ C$ | 8.8 |
| | | $T_A=70^\circ C$ | 7 |
| P_D | Maximum Power Dissipation | $T_A=25^\circ C$ | 2 |
| | | $T_A=70^\circ C$ | 1.3 |
| $R_{\theta JC}$ | Thermal Resistance-Junction to Case | - | $^\circ C/W$ |
| $R_{\theta JA}^{(3)}$ | Thermal Resistance-Junction to Ambient | 62.5 | $^\circ C/W$ |
| Drain-Source Avalanche Ratings | | | |
| $E_{AS}^{(4)}$ | Avalanche Energy, Single Pulsed | 9 | mJ |

Electrical Characteristics (T_A=25°C Unless Otherwise Noted)

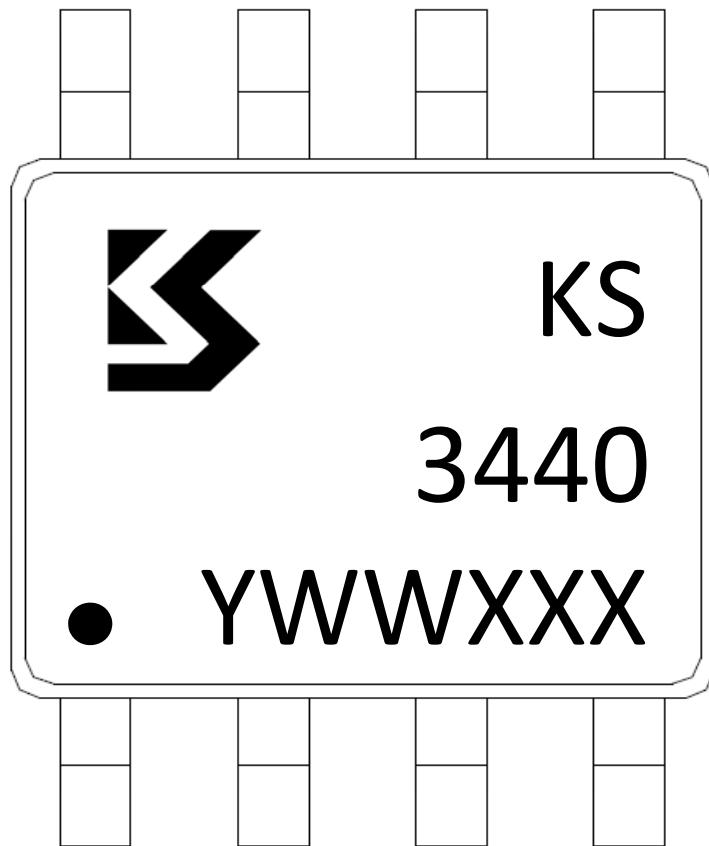
| Symbol | Parameter | Test Condition | KS3440HA | | | Unit |
|--|----------------------------------|---|----------|------|------|------|
| | | | Min. | Typ. | Max. | |
| Static Characteristics | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _{DS} =250μA | 30 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =30V, V _{GS} =0V | | | 1 | μA |
| | | T _J =125°C | | | 30 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _{DS} =250μA | 1 | 1.9 | 2.5 | V |
| I _{GSS} | Gate Leakage Current | V _{GS} =±20V, V _{DS} =0V | | | ±100 | nA |
| R _{DS(ON)} ^⑤ | Drain-Source On-state Resistance | V _{GS} =10V, I _{DS} =8A | | 16 | 19 | mΩ |
| | | V _{GS} =4.5V, I _{DS} =6A | | 24 | 29 | mΩ |
| Diode Characteristics | | | | | | |
| V _{SD} ^⑤ | Diode Forward Voltage | I _{SD} =8A, V _{GS} =0V | | 0.9 | 1.2 | V |
| t _{rr} | Reverse Recovery Time | I _{SD} =8A, dI _{SD} /dt=100A/μs | | 9.5 | | ns |
| Q _{rr} | Reverse Recovery Charge | | | 11.8 | | nC |
| Dynamic Characteristics^⑥ | | | | | | |
| R _G | Gate Resistance | V _{GS} =0V, V _{DS} =0V, F=1MHz | | 3.3 | | Ω |
| C _{iss} | Input Capacitance | V _{GS} =0V, V _{DS} =15V, Frequency=1.0MHz | | 455 | | pF |
| C _{oss} | Output Capacitance | | | 75 | | |
| C _{rss} | Reverse Transfer Capacitance | | | 60 | | |
| t _{d(ON)} | Turn-on Delay Time | V _{DD} =15V, I _{DS} =8A, V _{GEN} =10V, R _G =6Ω | | 7 | | ns |
| t _r | Turn-on Rise Time | | | 10 | | |
| t _{d(OFF)} | Turn-off Delay Time | | | 22 | | |
| t _f | Turn-off Fall Time | | | 7 | | |
| Gate Charge Characteristics^⑥ | | | | | | |
| Q _g | Total Gate Charge | V _{DS} =15V, V _{GS} =10V, I _{DS} =8A | | 11 | | nC |
| Q _{gs} | Gate-Source Charge | | | 3 | | |
| Q _{gd} | Gate-Drain Charge | | | 4 | | |

Notes:

- ①Pulse width limited by safe operating area.
- ②Calculated continuous current based on maximum allowable junction temperature.
- ③When mounted on 1 inch square copper board, t≤10sec. The value in any given application depends on the user's specific board design.
- ④Limited by T_{Jmax}, starting T_J = 25°C, L = 0.5mH, R_G = 25Ω, I_{AS} = 6A, V_{GS} = 10V.
- ⑤Pulse test; Pulse width≤300μs, duty cycle≤2%.
- ⑥Guaranteed by design, not subject to production testing.

Ordering and Marking Information

| Device | Package | Packaging | Quantity | Reel Size | Tape width |
|----------|---------|-----------|----------|-----------|------------|
| KS3440HA | SOP8 | Tape&Reel | 3000 | 13" | 12mm |

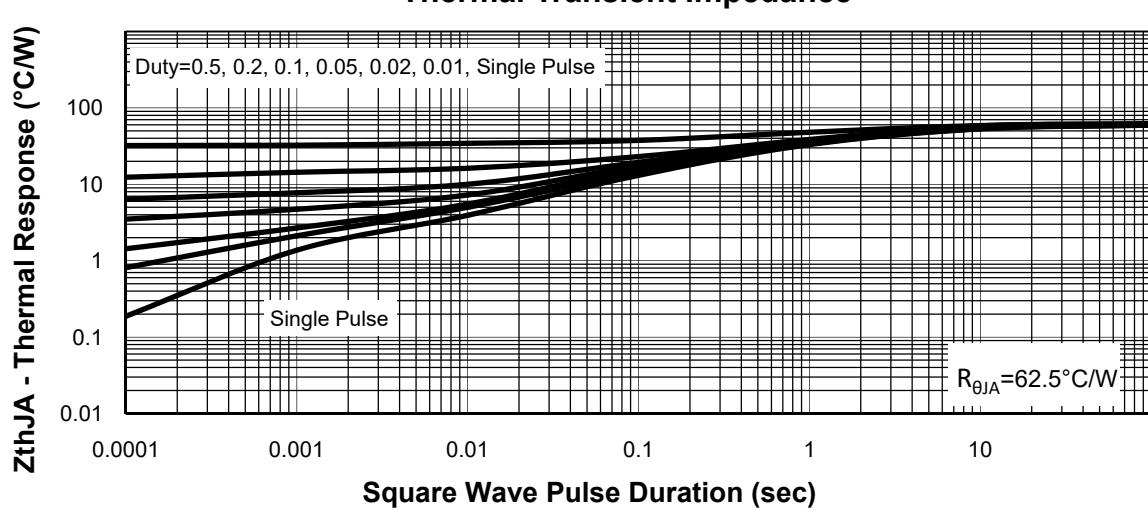
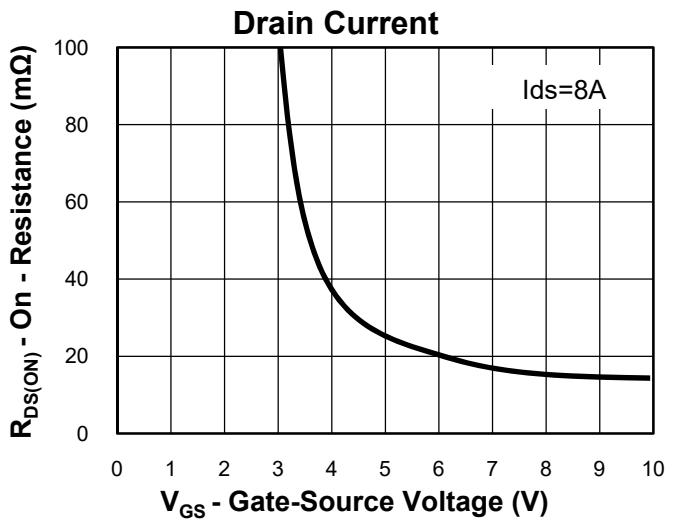
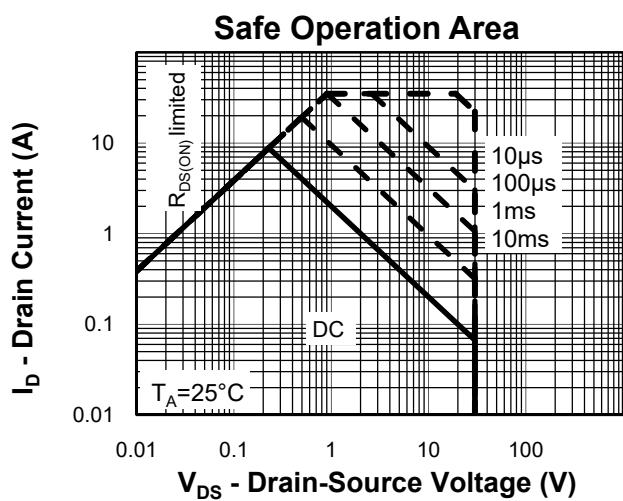
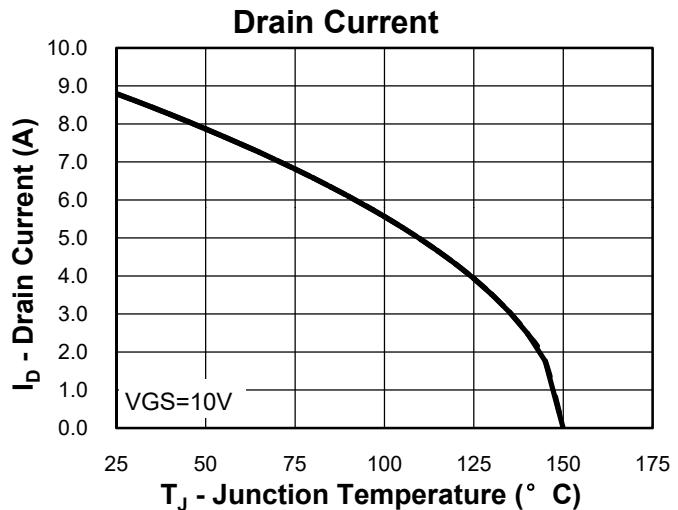
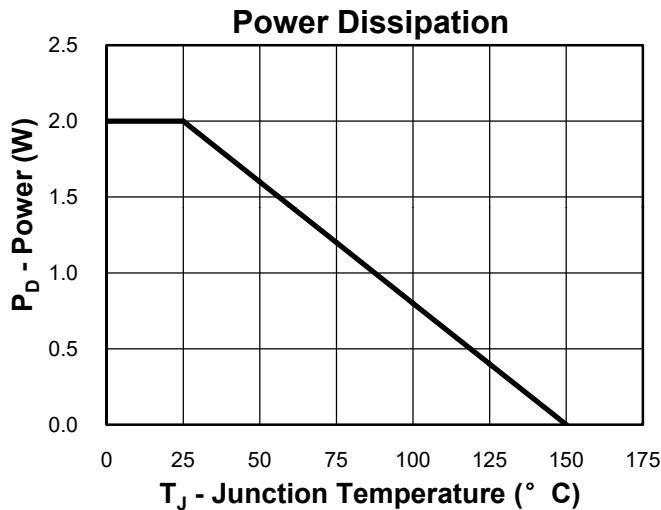


Y =Year,2017-A,2018-B,etc.

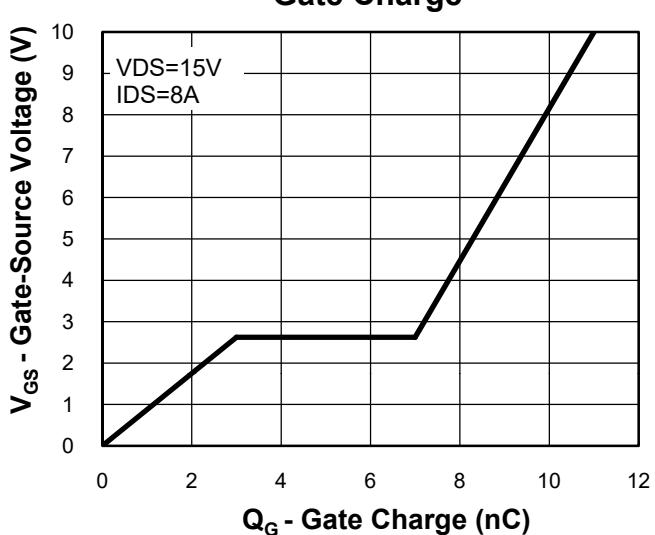
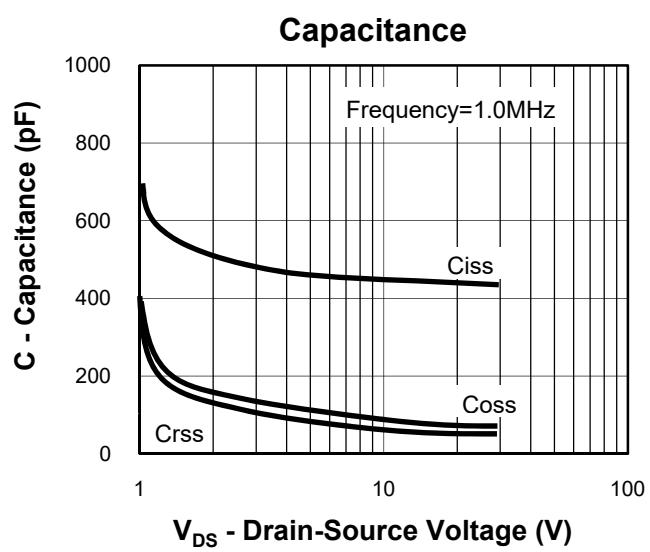
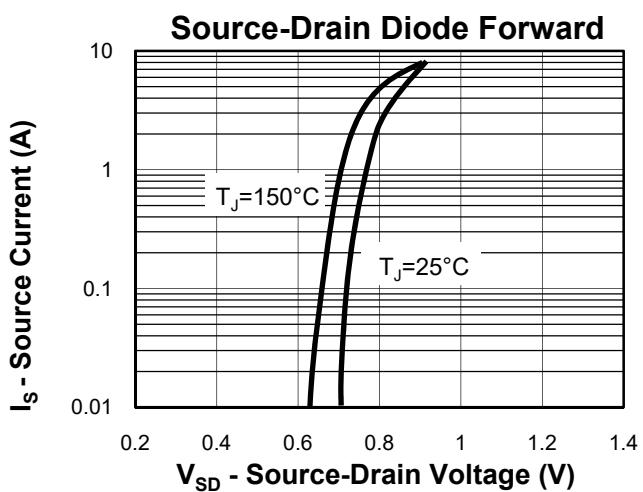
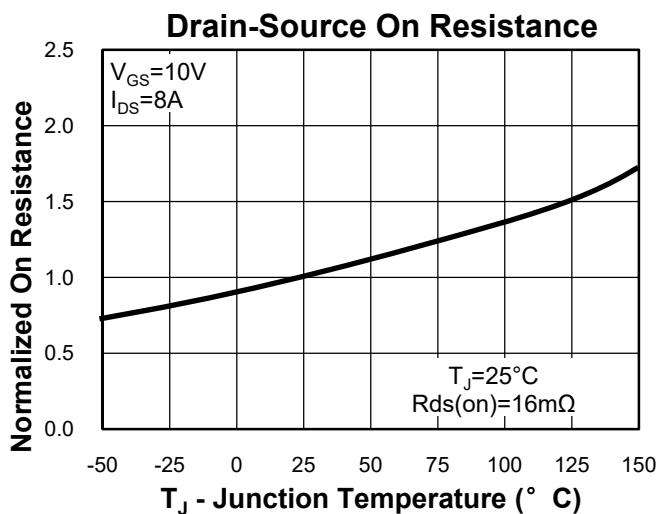
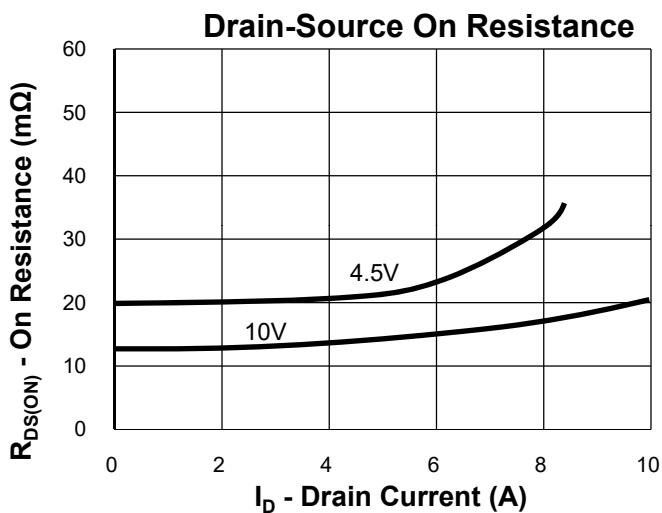
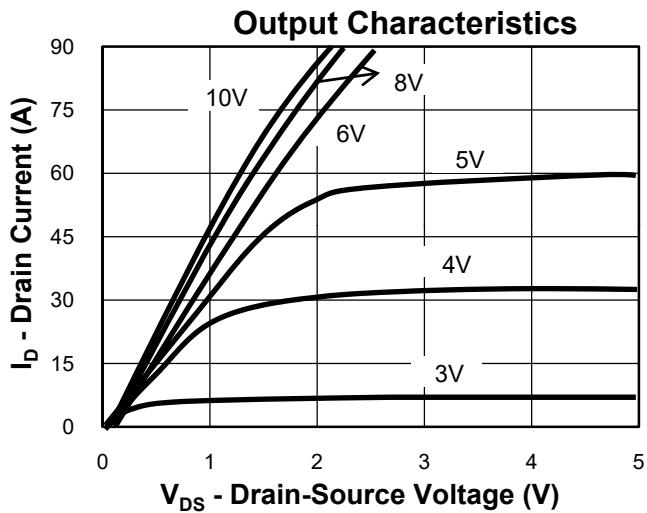
WW =Week.

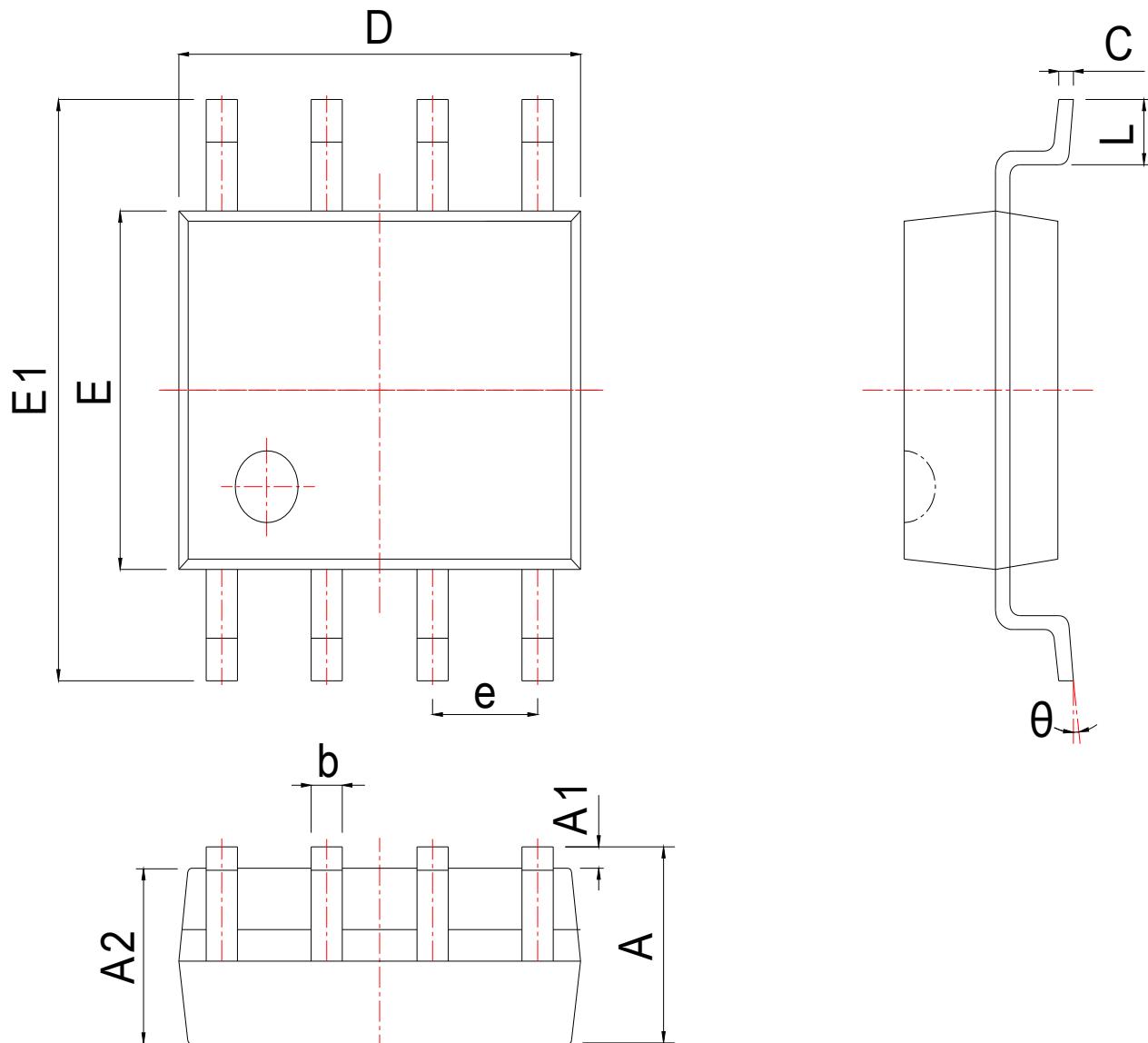
XXX =Lot number.

Typical Characteristics



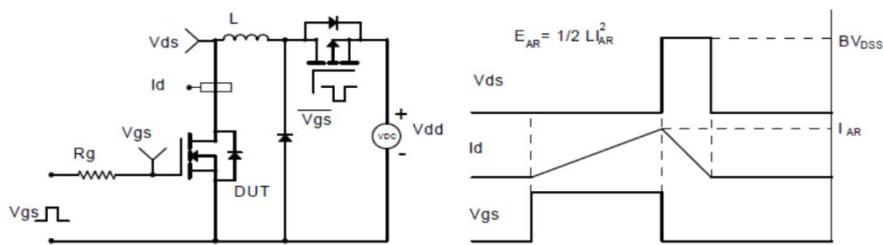
Typical Characteristics



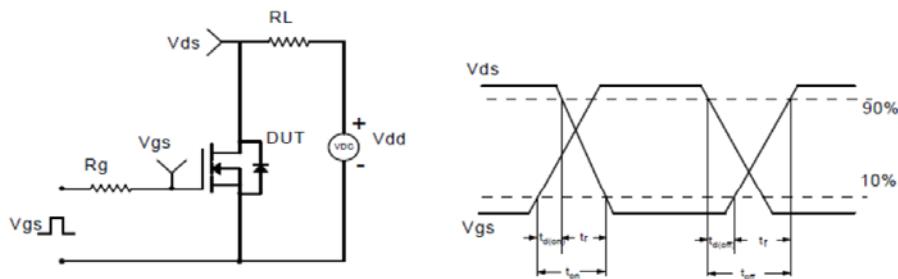
Package Information
SOP8


| SYMBOL | MM | | | INCH | | |
|--------|-----------|-------|-------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 1.300 | 1.525 | 1.750 | 0.051 | 0.060 | 0.069 |
| A1 | 0.050 | 0.150 | 0.250 | 0.002 | 0.006 | 0.010 |
| A2 | 1.350 | 1.450 | 1.550 | 0.053 | 0.057 | 0.061 |
| b | 0.330 | 0.420 | 0.510 | 0.013 | 0.017 | 0.020 |
| c | 0.170 | 0.210 | 0.250 | 0.007 | 0.008 | 0.010 |
| D | 4.700 | 4.900 | 5.100 | 0.185 | 0.193 | 0.201 |
| E | 3.800 | 3.900 | 4.000 | 0.150 | 0.154 | 0.157 |
| E1 | 5.800 | 6.000 | 6.200 | 0.228 | 0.236 | 0.244 |
| e | 1.270 BSC | | | 0.050 BSC | | |
| L | 0.400 | 0.835 | 1.270 | 0.016 | 0.033 | 0.050 |
| θ | 0° | | 8° | 0° | | 8° |

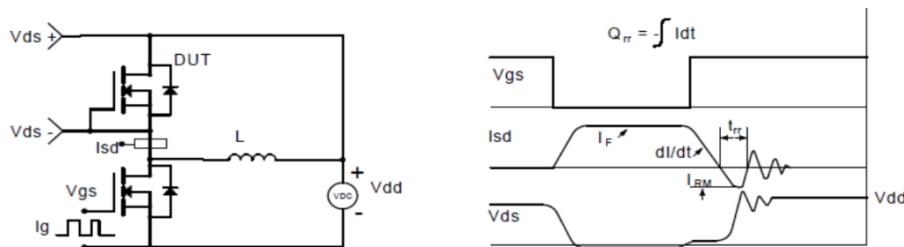
Avalanche Test Circuit and Waveforms



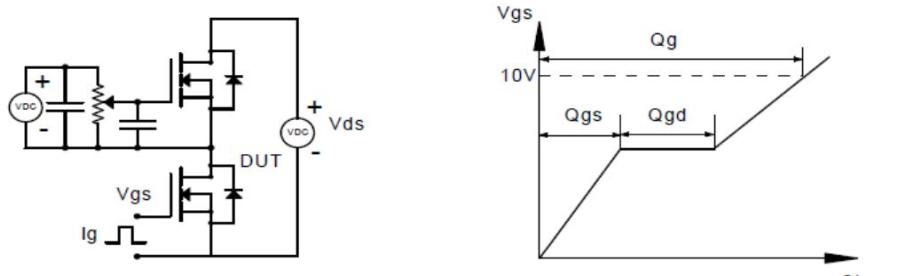
Switching Time Test Circuit and Waveforms



Diode Recovery Test Circuit and Waveforms



Gate Charge Test Circuit and Waveform



Customer Service

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